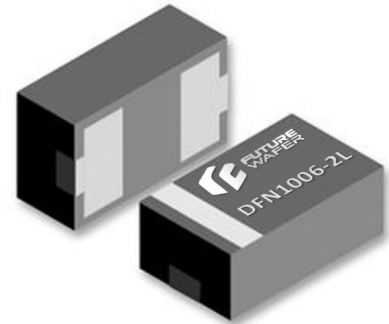
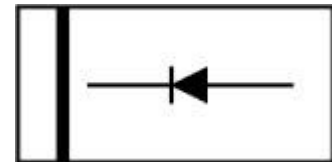


Applications

- Lan equipment
- Video
- DVI
- High Speed Data Line
- Ethernet
- USB 2.0 Power and Data line Protection



DFN1006-2L



Feature

- With TVS Diode
- ESD Protection: Level 4
- Low clamping voltage
- 300 Watts peak pulse power per line ($t_p=8/20\mu s$)
- Protection one line I/O port

IEC Compatibility

- EN61000-4
- 61000-4-2(ESD):Level 4,Contact: $\pm 30kV$,Air: $\pm 30kV$
- 61000-4-4(EFT):40A-5/50ns
- 61000-4-5(Surge):17A-8/20us

Mechanical Characteristics

- Molded JEDEC DFN1006 package
- Packing:Tape and Reel
- Flammability rating UL 94V-0
- Halgen Free

Device Characteristics

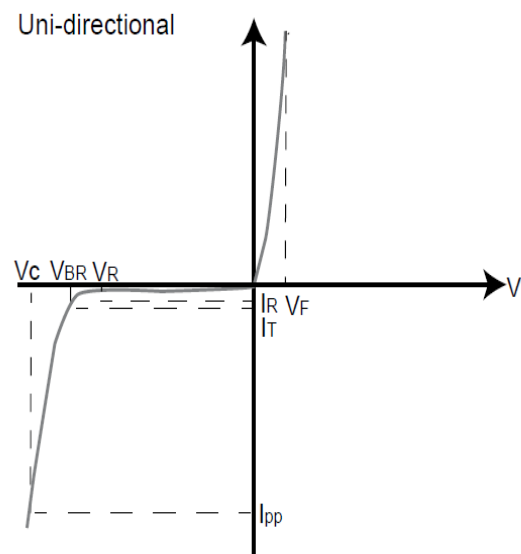
Maximum Ratings@25 unless otherwise specified			
Parameter	Symbol	Value	Units
Peak pulse power ($t_p=8/20\mu s$)	PPP	300	Watts
Operating Temperature	TJ	-55~150	$^{\circ}C$
Storage Temperature	TSTG	-55~150	$^{\circ}C$

Electrical Characteristics

Parameter	Symbol	Condition	min	Typ.	max	Units
Reverse Stand-off Voltage	VRWM	Pin 2 to 1			5	V
Reverse Breakdown Voltage	VBR	I _Z =1mA Pin2 to 1	6.3	6.7	7.1	V
Reverse Leakage Current	IR(max)	@VRWM			0.9	uA
Forward Voltage	VF(max)	IF=15mA			1.15	V
Clamping Voltage	VC	I _{PP} =1A tp=8/20us I _{PP} =17A tp=8/20us			9 18	V
Peak Pulse Current	I _{PP}	tp=8/20us			17	A
Junction Capacitance	C I/O	Pin capacitance to GND.Vdc=0V,f=1MHZ		70	100	pf

Electrical Characteristics T=(25°C)

Symbol	Parameter
V _{RWM}	Nominal Reverse Working Voltage
I _R	Reverse Leakage Current @ V _{RWM}
V _{BR}	Reverse Breakdown Voltage @ I _T
I _T	Test Current for Reverse Breakdown
V _C	Clamping Voltage @ I _{PP}
I _{PP}	Maximum Peak Pulse Current
C _{ESD}	Parasitic Capacitance
V _R	Reverse Voltage
f	Small Signal Frequency



Rating and characteristic curve

FIGURE 1
Power Derating Curve

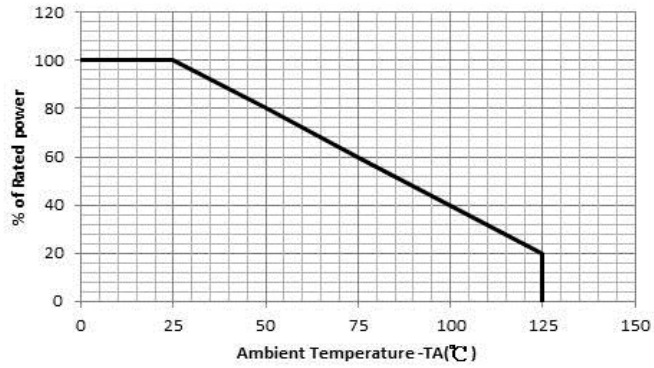
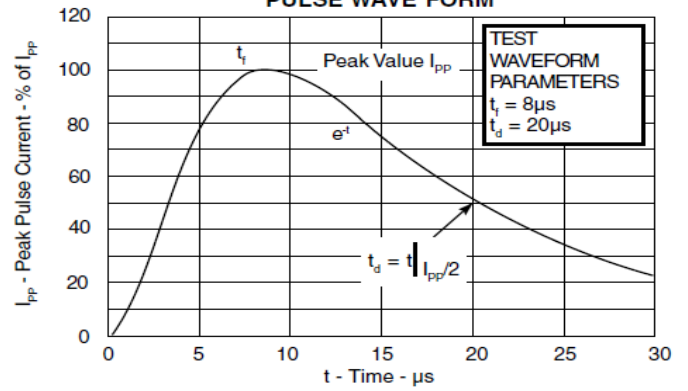
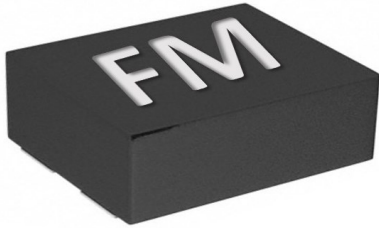


FIGURE 2
PULSE WAVE FORM



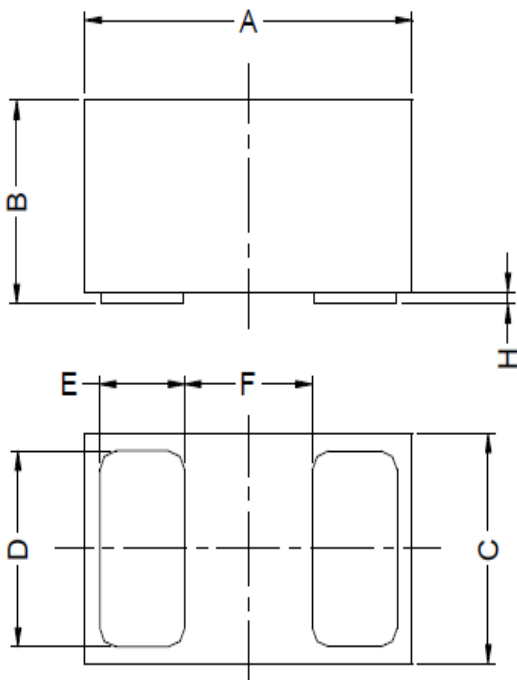
Ordering information

Marking codes



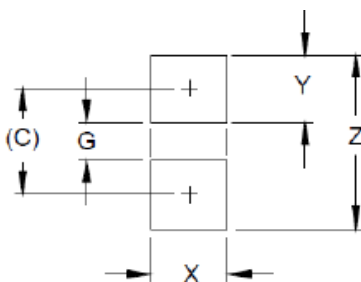
Part No.	Marking
FM05VL	FM
Quantity	5,000pcs

Package information



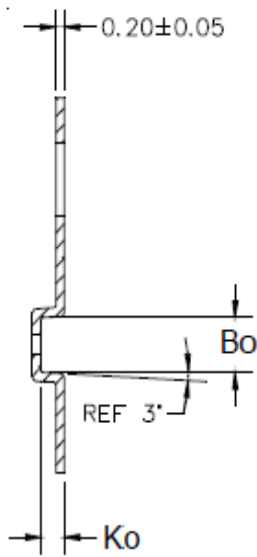
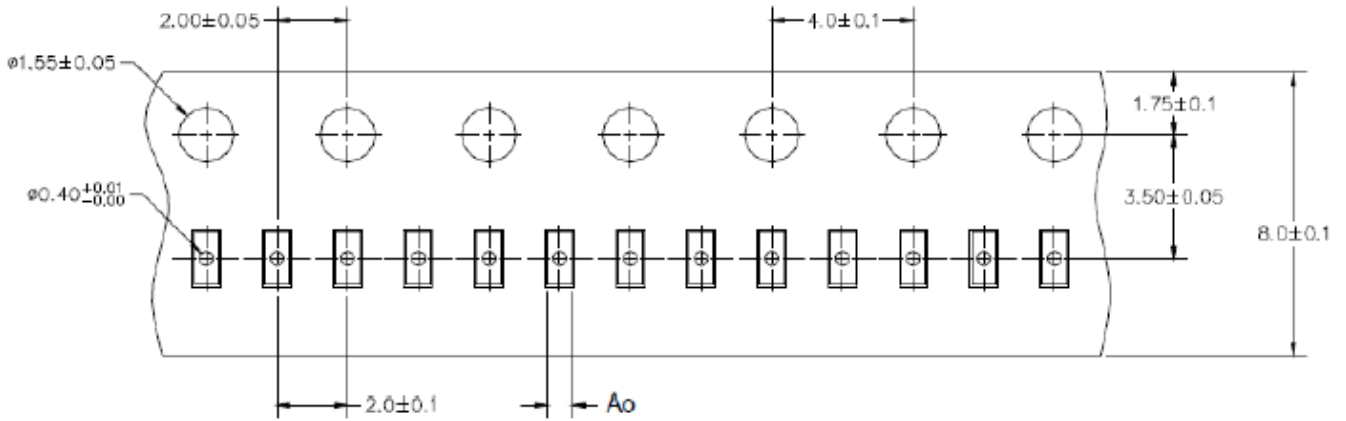
DFN1006-2			
Dim	Min	Typ	Max
A	0.95	1.00	1.075
B	0.47	0.50	0.53
C	0.55	0.60	0.675
D	0.45	0.50	0.55
E	0.20	0.25	0.30
F	-	0.40	-
H	0	0.03	0.05
All Dimensions in mm			

Pad Layout



DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.033)	(0.85)
G	.012	0.30
X	.024	0.60
Y	.022	0.55
Z	.055	1.40

Tape & Reel information



A0	B0	K0
0.69 +/-0.10 mm	1.19 +/-0.10 mm	0.66 +/-0.10 mm



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